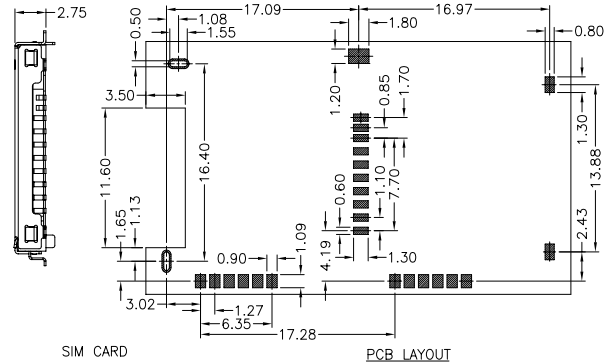
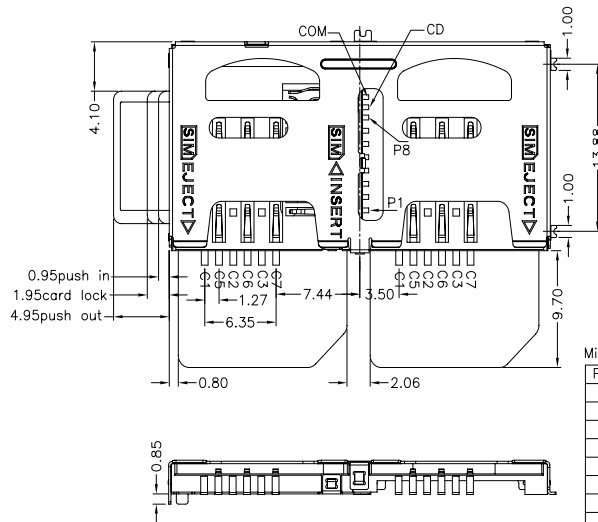




Part Number:101-00359-**
Double SIM + Micro SD Conn.

- Push-push eject type
- SMT
- Application for mobile phones

- 1.Materials:
 Housing: High temperature thermoplastic, UL 94V-0 rated.
 Contact: Copper alloy
 Cover: SUS304 over nickel plating (50U" min)
- 2.Contact finish:
 Selective 1~15u" gold plating on contact area, tin 160u" plating at solder tail, over nickel plating (50u"min)
- 3.Electrical specifications:
 Voltage Rating: 100VAC
 Current Rating: 0.5A per contact
 Dielectric strength: 500VAC initial and 250VAC final for one minute
 Insulation Resistance: 1000MΩ min at 500VDC
 Contact Resistance: 100mΩ max at 100mA
 Operating temperature: -25°C~+70°C
- 4.Mechanical specifications:
 Durability: 5000cycles.
 Micro SD Card Mating force: 13.8N max.
 Micro SD Card Unmating force: 1N max
 SIM Card Mating force: 10N max.
 Sim Card Unmating force: 0.3N max
- 5.RoHS Compliant



Micro-SD		SIM CARD	
PIN#	Name	PIN#	Name
1	DAT2	C1	VCC
2	CD/DAT3*	C2	RST
3	CMD	C3	CLK
4	VDD	C4	Reserved
5	CLK	C5	GND
6	Vss	C6	VPP
7	DAT0	C7	I/O
8	DAT1	C8	Reserved

